



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Appln. Of: MATSUDA

Serial No. 09/222,524

Filed: December 28, 1998

For: SEMICONDUCTOR DEVICE

Group: 2811

Examiner: N. Parekh

DOCKET: NEC N98039 CON

The Assistant Commissioner of Patents & Trademarks  
Washington, D.C. 20231

Dear Sir:

03/14/2002 ADSMAN1 00000093 09222524

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AMENDMENT D

This Amendment is being filed in response to the Official Action mailed December 13, 2001. Please amend the Application as follows:

IN THE CLAIMS:

Please amend independent claims 21-23, 27-29, 33-35 and 39-41 to read as follows:

21. (Amended) A semiconductor device comprising:
- a wiring substrate having a predetermined pattern of wiring formed on one surface;
  - a semiconductor chip disposed on the other surface of said wiring substrate and having at least one chip electrode set comprising at least two chip electrodes in a common wiring layer, wherein said chip electrodes are arranged from an edge of said semiconductor chip toward its inner side;
  - said wiring substrate having a number of through-holes;
  - a number of bumps formed respectively in said through-holes in conforming relationship with said at least two chip electrodes and electrically connecting said wiring with

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